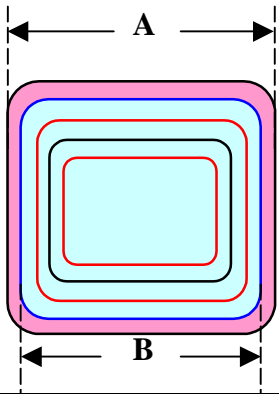


|  |                    |                               |             |       |
|--|--------------------|-------------------------------|-------------|-------|
| <b>Features :</b><br><ul style="list-style-type: none"> <li>* Extremely low forward volts</li> <li>* Guard ring protection</li> <li>* Low reverse leakage current</li> </ul>  | Chip size(A):      | 1.016 * 1.016 mm <sup>2</sup> |             |       |
|  | Bond Pad size(B) : | 0.889 * 0.889 mm <sup>2</sup> |             |       |
|  | Thickness :        | 300μm ± 20μm                  |             |       |
|  | Metalization :     | Anode Ti/Ni/Ag                |             |       |
|  | Metalization :     | Cathode Ti/Ni/Ag              |             |       |
| <b>Electrical Characteristics</b>  |                    | Sym.                          | Spec. Limit | Unit  |
| Maximum Instantaneous Forward Volt<br>at IF : 1.0Amp. 25°C   |                    | VF max                        | 0.40        | Volt  |
| Minimum Instantaneous Reverse Voltage<br>at IR : 300 uA 25°C   |                    | VR min.                       | 43          | Volt. |
| Minimum Non-repetitive Peak Surge current at 25°C  |                    | IFSM                          | 40          | Amp   |
| Storage Temperature  |                    | TSTG                          | -65 to +125 | °C    |

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